

Report NO.: MG00001000190

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	2N7000
Package Type :	TO-92

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.0263%
Lead Frame	Iron	7439-89-6	0.15%	
	Phosphorus	7723-14-0	0.04%	
	Copper	7440-50-8	99.80%	
	Silver	7440-22-4	0.01%	
Wire	copper	7440-50-8	99.99%	0.0192%
	others	/	0.01%	
Mold Compound	Quartz(SiO <sub>2</sub> )	14808-60-7	60.00%	50.2457%
	Silicon dioxide	7631-86-9	30.00%	
	Phenol-formaldehyde polymer	9003-35-4	9.50%	
	3-Trimethoxysilylpropane-1-thiol	4420-74-0	0.50%	
Plating	Tin	7440-31-5	100.00%	0.6293%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.